Overview

HP ProBook 445 G7 Notebook PC



Left

- 1. Internal Microphones (2)
- 2. Webcam
- 3. Privacy Shutter (Only available with webcam)
- 4. Webcam LED
- 5. Clickpad
- 6. Hard Drive LED

- 7. SD Card Reader
- 8. Thermal Vent
- 9. USB 2.0 Port
- 10. Standard Security Lock Slot (Lock sold separately)
- 11. Power Button

Overview



Right

- 1. Power Connector
- 2. USB Type-C® 3.1 Gen 2 (Alt Mode) Port
- 3. Ethernet Port (RJ-45)
- 4. HDMI Port (Cable not included)

- 5. USB 3.1 Gen 1 Port
- 6. USB 3.1 Gen 1 Port
- 7. Headphone / Microphone Combo Jack
- 8. HP Fingerprint Sensor (select models)

Overview

At a Glance

- Preinstalled Windows 10 or FreeDOS
- Choice of AMD RyzenTM 4000 series mobile processors, R7, R5 and R3
- Display include your choice of 35.56 cm (14.0") diagonal HD, Ultra Wide Viewing Angle FHD, And Privacy Panel option
- Enhanced security features including TPM2.0, HP Sure Sense, HP Sure Start, HP BIOSphere, Hardware enforced Firmware Protection, optional Fingerprint sensor (select models)⁴, optional IR camera, and optional Privacy Panel
- Designed to pass MIL-STD 810H testing¹
- Weight starting at 3.53 lb (1.6kg) (Weight will vary by configuration)
- HP Long-Life Rechargeable battery, with HP Fast Charge Technology recharges 50% in 30 minutes²
- Up to 512 GB Solid State Drives and 1 TB Hard Drive
- Up to 32 GB total system memory
- 720p HD webcam, IR camera for face authentication with Windows Hello
- Spill-resistant and optional backlit Keyboard³, and Clickpad with multi-touch gestures enabled, taps enabled as default
 - MIL STD 810H testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Damage under the MIL STI test conditions or any accidental damage requires an optional HP Accidental Damage Protection Care Pack.
 - 2. Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode when used with the power adapter provided with the notebook. After charging has reached 50% capacity, charging speed will return to normal. Charging time may vary +/-10% due to System tolerance.
 - 3. Backlit keyboard is an optional feature that must be configured at purchase.
 - 4. HP Fingerprint Sensor is an optional feature and requires configuration at purchase.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



PRODUCT NAME

HP ProBook 445 G7 Notebook PC

OPERATING SYSTEMS

Preinstalled Windows® 10 Pro 64¹

Windows® 10 Pro 64 (National Academic License)2

Windows® 10 Home 641

Windows® 10 Home Single Language 64¹ Windows® 10 Enterprise 64 (Web Support)¹

FreeDOS

- 1. Not all features are available in all editions or versions of Window. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/.
- 2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD® 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282

PROCESSORS

AMD RyzenTM 3 4300U APU with AMD RadeonTM Graphics (2.7 GHz base clock, up to 3.7 GHz max boost clock, 4 MB L3 cache, four-cores)^{3,4,5,6}

AMD RyzenTM 5 4500U APU with AMD RadeonTM Graphics (2.3 GHz base clock, up to 4.0 GHz max boost clock, 8 MB L3 cache, six-cores)^{3,4,5,6}

AMD RyzenTM 7 4700U APU with AMD RadeonTM Graphics (2.0 GHz base clock, up to 4.1 GHz max boost clock, 8 MB L3 cache, eight cores)^{3,4,5,6}

AMD RyzenTM 5 PRO 4650U APU with RadeonTM Graphics (2.1 GHz base clock, up to 4 GHz max boost clock, 8 MB L3 cache, 6 cores)^{3,4,5}

AMD RyzenTM 7 PRO 4750U APU with RadeonTM Graphics (1.7 GHz base clock, up to 4.1 GHz max boost clock, 8 MB L3 cache, 8 cores)^{3,4,5}

Processors Family

AMD RyzenTM 4000 Series Mobile processors⁶

- 3. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
- 4. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. AMD's numbering is not a measurement of clock speed.
- 5. AMD Max Burst frequency performance varies depending on hardware, software and overall system configuration.
- 6. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on production configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on

Technical Specifications

http://www.support.hp.com.

CHIPSET

Chipset is integrated with processor

GRAPHICS

Integrated

AMD RadeonTM Graphics⁷

Note: View processor section for details.

Supports

Support HD decode, DX12, HDMI 1.4

7. HD content required to view HD images.

DISPLAYS

Internal

Non-Touch

35.56 cm (14") diagonal HD SVA eDP anti-glare LED backlit slim, 220 cd/m², 45% NTSC (1366 x 768)^{7,8}
35.56 cm (14") diagonal HD SVA eDP anti-glare LED backlit slim, 220 cd/m², 45% NTSC for HD camera (1366 x 768)^{7,8}
35.56 cm (14") diagonal HD SVA eDP anti-glare LED backlit slim, 220 cd/m², 45% NTSC for HD + IR camera (1366 x 768)^{7,8}
35.56 cm (14") diagonal FHD IPS eDP anti-glare LED-backlit slim, 250 cd/m², 45% NTSC (1920 x 1080)^{7,8}
35.56 cm (14") diagonal FHD IPS eDP anti-glare LED-backlit slim, 250 cd/m², 45% NTSC for HD camera (1920 x 1080)^{7,8}
35.56 cm (14") diagonal FHD IPS eDP anti-glare LED-backlit slim, 250 cd/m², 72% NTSC for HD Webcam Privacy (1920x1080)^{7,8}

Supports narrow bezel

HDMI

HDMI 1.4 up to 4K 30Hz

- 7. HD content required to view HD images.
- 8. Resolutions are dependent upon monitor capability, and resolution and color depth settings.
- 9. HP Sure View integrated privacy screen is an optional feature that must be configured at purchase and is designed to function landscape orientation.



Docking station model	Total number of supported displays (incl. the notebook display)	Max. resolutions supported	Dock Connectors	Technical limitations
HP Thunderbolt Dock 120W G2	3	Dual 4k @60Hz	2xDP, 1xVGA, 1xTB,1xUSB-C alt-mode	Dual 4k only with one display in to DP and + TB port or USB-C alt mode + TB port
HP USB-C Dock G4	3	Dual 2K @ 60Hz Single 4K @ 60Hz (3840 x 1440)	1xHDMI, 2xDP	
HP USB-C Universal Dock	3	Dual 4K @ 60Hz Single 5K @ 60Hz	2xDP	
HP USB-C Travel Dock	2	Single 2K @ 60Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time
HP USB-C Mini Dock	2	Single 4K @ 30Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time
HP USB-C/A Universal Dock G2	3	Dual 2.5K @ 60Hz	2xDP, 1xHDMI	
HP USB-C Dock G5	3	Dual 2.5K @ 60Hz or 4K @ 60Hz + FHD @ 60Hz	2xDP, 1xHDMI	

STORAGE AND DRIVES

Primary Storage

500 GB 7200 rpm SATA¹⁰ 1 TB 5400 rpm SATA¹⁰

Primary M.2 Storage

128 GB SATA TLC Solid State Drive¹⁰
256 GB PCIe® NVMeTM Value Solid State Drive¹⁰
512 GB PCIe® NVMeTM TLC Solid State Drive¹⁰
512 GB PCIe® NVMeTM Value Solid State Drive¹⁰

Note: PCIe SSD not available for Celeron

10. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) reserved for system recovery software.

MEMORY



Maximum Memory

32 GB DDR4-3200 SDRAM16¹¹

Memory

32 GB DDR4-3200 SDRAM (2 x 16 GB)¹¹
16 GB DDR4-3200 SDRAM (2 x 8 GB)¹¹
16 GB DDR4-3200 SDRAM (1 x 16 GB)¹¹
12 GB DDR4-3200 SDRAM (1 x 4 GB and 1 x 8 GB)¹¹
8 GB DDR4-3200 SDRAM (1 x 8 GB)¹¹
8 GB DDR4-3200 SDRAM (2 x 4 GB)¹¹
4 GB DDR4-3200 SDRAM (1 x 4 GB)¹¹

Memory Slots

2 SODIMM

Both slots are customer accessible / upgradeable by IT or self-maintainers only DDR4 PC4 SODIMMS, system runs at 3200 Supports Dual Channel Memory

11. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

WLAN

Realtek RTL8822CE 802.11 a/b/g/n/ac (2x2) Wi-Fi® + Bluetooth® 5 Combo¹²
Intel® Dual Band Wi-Fi® 6 AX200 802.11ax (2x2) and Bluetooth® 5 Combo, non-vPro^{TM12}
Intel® Dual Band Wireless-AC 9260 802.11 a/b/g/n/ac (2x2) Wi-Fi® and Bluetooth® 5 Combo, non-vPro^{TM12}

Ethernet

Realtek RTL8111EP 10/100/1000 NIC13

12. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If th final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported.

13. The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

AUDIO/MULTIMEDIA



Audio

Integrated microphone (Mono or Dual Array)
2 Integrated stereo speakers

Camera

720p HD camera⁷ 720p HD + IR camera^{7,14}

7. HD content required to view HD images.

14. IR camera is an optional feature that must be configured at purchase.

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Keyboard, spill-resistant with optional backlit¹⁵

Pointing Device

Clickpad with multi-touch gesture support

Function Keys

F1 - Display Switching

F2 - Blank or SureView On/Off

F3 - Brightness Down

F4 - Brightness Up

F5 - Audio Mute

F6 - Volume Down

F7 - Volume Up

F8 - Mic Mute

F9 - Blank or Backlit Toggle

F10 - numlk

F11 - Wireless

F12 - Sleep

Hidden Function Keys

Fn+R - Break

Fn+S - Sys Rq

Fn+C - Scroll Lock

15. Backlit keyboard is an optional feature that must be configured at purchase.

SOFTWARE AND SECURITY

BIOS

HP BIOSphere Gen5¹⁶

HP Drive Lock & Automatic Drive Lock¹⁷

BIOS Update via Network

Master Boot Record Security

Technical Specifications

Power On Authentication

Secure Erase¹⁸

Absolute Persistence Module¹⁹

Pre-boot Authentication

Software

HP Connection Optimizer

HP Image Assistant

HP Hotkey Support

HP JumpStarts

HP Support Assistant²⁰

HP Noise Cancellation Software

Buy Office (sold separately)

Manageability Features

HP Driver Packs²¹

HP System Software Manager (SSM)

HP BIOS Config Utility (BCU)

HP Client Catalog

HP Manageability Integration Kit Gen3²²

Client Security Software

HP Client Security Manager Gen5²³

HP Fingerprint Sensor²⁴

Windows Defender²⁵

Security Management

Pre-boot Authentication

TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified) (FIPS 140-2 Level 2 Certified)

USB enable/disable (via BIOS)

Power-on password (via BIOS)

Setup password (via BIOS)

HP Fingerprint Sensor²⁴

Support for chassis padlocks and cable lock devices

HP Sure Click²⁶

HP Sure Sense²⁷

HP Sure Start Gen5²⁸

16. HP BIOSphere Gen5 is available on select HP Pro and Elite PCs. See product specifications for details. Features may vary depending on the platform and configurations.

17. HP Drive Lock & Automatic Drive Lock is not supported on NVMe drives

18. For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® OptaneTM.

19. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/ computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to

Technical Specifications

use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

20. HP Support Assistant requires Windows and Internet access.

21. HP Driver Packs not preinstalled, however available for download at

http://www.hp.com/go/clientmanagement.

- 22. HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.
- 23. HP Client Security Manager Gen5 requires Windows and is available on the select HP Pro and Elite PCs. See product specifications for details.
- 24. HP Fingerprint Sensor is an optional feature and requires configuration at purchase.
- 25. Windows Defender Opt in and internet connection required for updates.
- 26. HP Sure Click is available on select HP platforms and supports Microsoft® Internet Explorer, Google Chrome, and ChromiumTM. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode. Check http://h20195.www2.hp.com/v2/GetDocument.aspx?docname=4AA7-0922ENW for all compatible platforms as they become available.
- 27. HP Sure Sense requires Windows 10. See product specifications for availability.
- 28. HP Sure Start Gen5 is available on select HP PCs with Intel processors. See product specifications for availability.

POWER

Power Supply

HP Smart 65 W External AC power adapter²⁹
HP Smart 65 W EM External AC power adapter²⁹
HP Smart 65 W USB Type-C[®] adapter²⁹
HP Smart 45 W External AC power adapter²⁹
HP Smart 45 W USB Type-C[®] adapter²⁹

Primary Battery

HP Long Life 3-cell, 45 Wh Li-ion polymer³⁰

Power Cord

3-wire plug - 1.8 m²⁹
3-wire plug - 1.0 m²⁹
2-wire plug - 1.0 m²⁹
Duckhead power cord - 1.0 m²⁹
Duckhead power cord - 1.8 m²⁹

Battery life

15 hours and 15 minutes³¹

Battery Weight

0.22 kg 0.49 lb

- 29. Availability may vary by country.
- 30. Battery is internal and not replaceable by customer. Serviceable by warranty.
- 31. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See http://www.bapco.com for additional details.

Technical Specifications

WEIGHTS & DIMENSIONS

Product Weight

Starting at 3.53 lb32 Starting at 1.6 kg³²

Product Dimensions (w x d x h)

12.76 x 9.36 x 0.71 in 32.42 x 23.77 x 1.79 cm

32. Weight will vary by configuration. Does not include power adapter.

PORTS/SLOTS

1 USB 3.1 Type-C[®] Gen 2 (Power delivery, DisplayPortTM 1.2)

2 USB 3.1 Gen 1

1 USB 2.0 (powered port)

1 HDMI 1.4³³

1 RJ-45

1 AC power

1 stereo headphone/microphone combo jack

Expansion Slots

1 SD

Supports SD, SDHC, SDXC

33. HDMI cable sold separately.

ENVIRONMENTAL & INDUSTRY

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: • IT ECO declaration • US ENERGY STAR® • EPEAT® 2019 Gold in U.S. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit http://www.epeat.net for more information.			
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".			
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz	
Normal Operation (Short idle)	4.14 W	4.164 W	4.056 W	
Normal Operation (Long idle)	2.112 W 2.184 W 2.076 W			
Sleep	0.372 W 0.384 W 0.372 W			
Off	0.192 W	0.228 W	0.192 W	

Technical Specifications

	Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.			
Heat Dissipation*	115VAC, 60Hz 230VAC, 50Hz		100VAC, 50Hz	
Normal Operation (Short idle)			14 BTU/hr	
Normal Operation (Long idle)	7 BTU/hr 7 BTU/hr 7 BT		7 BTU/hr	
Sleep	1 BTU/hr	1 BTU/hr	1 BTU/hr	
Off	1 BTU/hr	1 BTU/hr	1 BTU/hr	
	Heat dissipation is calculated based on hour.	the measured watts, assuming	g the service level is attained for or	
Declared Noise	Sound Power		Sound Pressure	
Emissions	(L _{WAd} , bels)		(L _{pAm} , decibels)	
(in accordance with ISO 7779 and ISO 9296)				
Typically Configured - Idle	2.5		25	
Fixed Disk - Random writes	2.5		25	
Upgrading Batteries	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: 3 USB ports 1 PC card slot (type I/II) 1 ExpressCard/54 slot 1 IEEE 1394 Port 2 SODIMM memory slots Optional expansion base docking station 1 multi-bay II storage port Interchangeable HDD Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.			
	This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight Battery size: Not Applicable			
Additional Information	 Battery type: Not Applicable This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680.1 (EPEAT) standard at the <gold> level, see http://www.epeat.net</gold> Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and 			

Technical Specifications

Technical Specification	ons			
	ISO1043. This product contains 2.4% post-consumer recycled plastic (by wt.) This product is 96.2% recycle-able when properly disposed of at end of life.			
Packaging Materials		PAPER/Paper	51 g	
		PAPER/Corrugated	230 g	
	Internal:	PLASTIC/Polyethylene Expanded - EPE	31 g	
		PLASTIC/Polyethylene low density - LDPE	9 g	
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants - may not be used as flame retardants in plastics			
	Cadmium Chlorinated Hydrocarbons Chlorinated Paraffins Formaldehyde Halogenated Diphenyl Methanes Lead carbonates and sulfates Lead and Lead compounds Mercuric Oxide Batteries Nickel - finishes must not be used on the external surface designed to be frequently handled or carried by the user. Ozone Depleting Substances Polybrominated Biphenyls (PBBs) Polybrominated Biphenyl Ethers (PBBEs) Polybrominated Biphenyl (PCB) Polychlorinated Biphenyl (PCB) Polychlorinated Terphenyls (PCT) Polyvinyl Chloride (PVC) - except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO) HP follows these guidelines to decrease the environmental impact of product packaging: Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.			
Packaging Usage				
End-of-life Management and Recycling	your product, p Products return The EU WEEE for each produ instructions) is These instruct	nd-of-life HP product return and recycling programs lease go to: http://www.hp.com/go/reuse-recycle or ned to HP will be recycled, recovered or disposed of in directive (2002/95/EC) requires manufacturers to act type for use by treatment facilities. This informations posted on the Hewlett Packard web site at: http://ions.may.be.used.by.recyclers.and.other.WEEE.tu.	r contact your nearest HP sales officent a responsible manner. provide treatment information ation (product disassembly //www.hp.com/go/recyclers.	
HP Inc. Corporate Environmental	OEM customers who integrate and re-sell HP equipment. For more information about HP's commitment to the environment: Global Citizenship Report			

Technical Specifications

Information http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/

PC_GBU_Product_Design_ISO_14K_Certificate.pdf

and

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)

Nominal Operating Voltage 19V Average Operating Power 7.52 W

Integrated graphics Yes (AMD RadeonTM Graphics)

Max Operating Power Discrete < 65W UMA < 45W

Temperature

Operating 32° to 95° F (0° to 35° C) (not writing optical) Non-operating 41° to 95° F (5° to 35° C) (writing optical)

Relative Humidity

Operating 10% to 90%, non-condensing

Non-operating 5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature

Shock

Operating 40 G, 2 ms, half-sine Non-operating 200 G, 2 ms, half-sine

Random Vibration

Operating 0.75 grms
Non-operating 1.50 grms

Altitude (unpressurized)

Operating -50 to 10,000 ft (-15.24 to 3,048 m) Non-operating -50 to 40,000 ft (-15.24 to 12,192 m)

Planned Industry Standard Certifications

UL Yes
CSA Yes
FCC Compliance Yes

ENERGY STAR® Selected models³⁴
EPEAT® 2019 Yes, Gold in U.S.³⁵

ICES Yes
Australia Yes
NZ A-Tick Compliance Yes
CCC Yes
Japan VCCI Compliance Yes
KC Yes
BSMI Yes
CE Marking Compliance Yes

Technical Specifications

BNCI or BELUS Yes
CIT Yes
GOST Yes
Saudi Arabian Compliance (ICCP) Yes
SABS Yes

- 34. Configurations of the HP ProBook 445 G7 that are ENERGY STAR® qualified are identified as HP ProBook 445 G7 ENERGY STAR on HP websites and on http://www.energystar.gov.
- 35. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit http://www.epeat.net for more information.

DISPLAYS

Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Panel LCD 14 inch diagonal HD (1366 x 768) Anti-Glare WLED SVA 45% NTSC 220 nits eDP 1.2 w/o PSR slim NB non-touch Outline Dimensions (W x H x D) 316.2 x 198.04 (max.)
Active Area 309.4 x 173.95
Weight <280 g max.
Diagonal Size 14.0 (inch)
Thickness 3.0 mm max
Interface eDP 1.2 (1 lane)
Surface Treatment Anti-Glare

Touch Enabled No
Contrast Ratio 300:1 (typ)

Refresh Rate 60 Hz

Brightness 220 nits typical (Panel Only)

Pixel Resolution 1366 x 768 (HD)

Format of LCD Pixel Arrangement RGB Backlight LED

Color Gamut Coverage45% of NTSCColor Depth6 bits + Hi FRCViewing AngleSVA 40/40/15/30

Technical Specifications

Panel LCD 14 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 45% NTSC 250 nits eDP slim NB

 Outline Dimensions (W x H x D)
 316.17 x 197.98 mm (max)

 Active Area
 309.37 x 174.02 mm (typ.)

Weight 285 g (max)

Diagonal Size 14.0 inch

Thickness 3.0 mm (max)

Interface eDP 1.2 (2 lane)

Surface Treatment Anti-Glare

Touch Enabled No

Contrast Ratio600:1 (typ.)Refresh Rate60 HzBrightness250 nits

Pixel Resolution 1920 x 1080 (FHD)

Format of LCD Pixel Arrangement RGB Backlight LED

Color Gamut Coverage 45% of NTSC

Color Depth 6 bits

Viewing Angle UWVA 85/85/85

Panel LCD 14 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 72% NTSC 1000 nits eDP 1.4+PSR2 flat Privacy

Outline Dimensions (W x H x D) 315.3

Active Area

315.31 x 195.498 mm (max) 309.312 x 173.988 mm (typ.)

Weight 265 g (max)

Diagonal Size 14 inch

Thickness 3.0 mm (max)

Interface eDP 1.4 + PSR2 (4 lane)

Surface Treatment Anti-Glare

Touch Enabled No

Contrast Ratio 2000:1 (typ.)
Refresh Rate 60 Hz

Brightness 1000 nits

Pixel Resolution 1920 x 1080 (FHD)

Format of LCD Pixel Arrangement RGB Backlight LED

Color Gamut Coverage 72% of NTSC

Color Depth 8 bit

STORAGE AND DRIVES

For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserve for system recovery software

Technical Specifications

500 GB 7200 rpm SATA Hard

Drive Weight

0.20 lbs (92 g) ~ 0.21 lbs (95 g)

Drive

Rotation Speed 7200 rpm

Cache Buffer Up to 32 MB

Height 0.28 in (7 mm)

Width 2.75 in (69.85 mm)

Interface ATA-8, SATA 3.0

Transfer Rate 600 MB/s

Seek Time Single Track: 2 ~ 1.5 ms

Average: 11 ~ 13 ms Maximum: 18 ~ 22 ms

Logical Blocks 976,773,168

Operating Temperature 32° to 140° F (0° to 60° C) [top cover temp]

Security Features ATA Security

Features S.M.A.R.T., NCQ, Ultra DMA

1 TB 5400 rpm SATA Hard Drive Drive Weight 0.21 lbs (94 g)

Rotation Speed 5400 rpm

Cache Buffer Up to 32 MB

Height 0.28 in (7.2 mm)

Width 2.75 in (69.85 mm)

Interface ATA-8, SATA 3.0

Transfer Rate 600 MB/s

Seek Time Single Track2 ms

Average12 ~ 13 ms Maximum18 ~ 22 ms

Logical Blocks 1,953,525,168

Operating Temperature 32° to 140° F (0° to 60° C) [top cover temp]

Security Features ATA Security

Features S.M.A.R.T., NCQ, Ultra DMA

SSD 128 GB 2280 M2 SATA-3 Form Factor

TLC

Form Factor M.2 2280
Capacity 128 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 ATA-8, SATA 3.0

 Maximum Sequential Read
 Up To 520 MB/s

 Maximum Sequential Write
 Up To 450 MB/s

 Logical Blocks
 250,069,680

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features DIPM; TRIM; DEVSLP

Technical Specifications

256 GB 2280 PCIe NVMe Value Solid State Drive Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

Height0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCIe NVMe Gen3Maximum Sequential ReadUp To 1700 MB/sMaximum Sequential WriteUp To 1300 MB/sLogical Blocks500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

512 GB 2280 M2 PCIe NVMe TLC Solid State Drive Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

Height0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCIe NVMe Gen3X4Maximum Sequential ReadUp To 2600 MB/sMaximum Sequential WriteUp To 1400 MB/sLogical Blocks1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

512 GB 2280 PCIe NVMe Value Solid State Drive Form Factor M.2 2280
Capacity 512 GB
NAND Type Value

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

Maximum Sequential ReadUp To 1500 ~ 1700 MB/sMaximum Sequential WriteUp To 860 ~ 1500 MB/s

Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security, TRIM; L1.2

NETWORKING/COMMUNICATIONS

WLAN

Intel® Wi-Fi 61 AX200 and Wireless LAN Standards IEEE 802.11a

Technical Specifications

Bluetooth® 5.0 802.11ax (2x2) non-vPro, supporting gigabit file transfer speeds) non-vPro IEEE 802.11b
IEEE 802.11g
IEEE 802.11n
IEEE 802.11ac
IEEE 802.11d
IEEE 802.11d
IEEE 802.11t
IEEE 802.11h
IEEE 802.11i
IEEE 802.11k
IEEE 802.11r
IEEE 802.11v

Interoperability

Frequency Band

Wi-Fi CERTIFIEDTM

• 802.11b/g/n/ax

2.402 - 2.482 GHz

802.11a/n/ac/ax
 4.9 - 4.95 GHz (Japan)

5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz

Data Rates

- 802.11b: 1, 2, 5.5, 11 Mbps
- 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
- 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
- 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
- 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)

Modulation

Direct Sequence Spread Spectrum

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM

Security³

- IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only
- AES-CCMP: 128 bit in hardware
- 802.1x authentication
- WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
- WPA2 certification
- IEEE 802.11i
- WAPI

Network Architecture

Models

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

Roaming

Output Power²

IEEE 802.11 compliant roaming between access points

- 802.11b: +18.5dBm minimum
- 802.11g: +17.5dBm minimum
- 802.11a: +18.5dBm minimum
- 802.11n HT20(2.4GHz): +15.5dBm minimum
- 802.11n HT40(2.4GHz): +14.5dBm minimum
- 802.11n HT20(5GHz): +15.5dBm minimum
- 802.11n HT40(5GHz): +14.5dBm minimum
- 802.11ac VHT80(5GHz): +11.5dBm minimum
- 802.11ac VHT160(5GHz): +11.5dBm minimum
- 802.11ax HT40(2.4GHz): +10dBm minimum
- 802.11ax VHT160(5GHz): +10dBm minimum

Technical Specifications

Power Consumption • Transmit mode 2.0 W

Receive mode 1.6 W

• Idle mode (PSP) 180 mW (WLAN Associated)

• Idle mode 50 mW (WLAN unassociated)

Connected Standby 10mW

Radio disabled 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity⁴ • 802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum
802.11a/g, 6Mbps: -86dBm maximum

802.11a/g, 54Mbps: -72dBm maximum

• 802.11n, MCS07: -67dBm maximum

802.11n, MCS15: -64dBm maximum
802.11ac, MCS0: -84dBm maximum

802.11ac, MCS0: -84dBm maximum
 802.11ac, MCS9: -59dBm maximum

• 802.11ax, MCS11(HT40): -59dBm maximum

• 802.11ax, MCS11(VHT160): -58.5dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard

Dimensions Type 2230: 2.3 x 22.0 x 30.0 mm

Type 1216: 1.67 x 12.0 x 16.0 mm

Weight Type 2230: 2.8 g

Type 126: 1.3 g

Operating Voltage 3.3v +/- 9%

Temperature Operating: 14° to 158° F (-10° to 70° C)

Non-operating: -40° to 176° F (-40° to 80° C)

Humidity Operating: 10% to 90% (non-condensing)

Non-operating: 5% to 95% (non-condensing)

Altitude Operating: 0 to 10,000 ft (3,048 m)

Non-operating: 0 to 50,000 ft (15,240 m)

LED Activity LED Amber - Radio OFF

LED OFF - Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2/5.0/5.1 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available Legacy: 0~79 (1 MHz/CH)

Channels BLE: 0~39 (2 MHz/CH)

Signaling Data Rate Legacy: 3 Mbps Signaling Data Rate 2.17 Mbps

BLE: 1 Mbps Signaling Data Rate 0.2 Mbps

1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with a

maximum transmit power of + 9.5 dBm for BR and EDR.

Technical Specifications

Peak (Tx) 330 mW **Power Consumption**

Peak (Rx) 230 mW

Selective Suspend 17 mW

Bluetooth Software

Supported **Link Topology** Microsoft Windows Bluetooth Software

Power Management Microsoft Windows ACPI, and USB Bus Support FCC (47 CFR) Part 15C, Section 15.247 & 15.249 Certifications

Power Management ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 Certifications

UL. CSA. and CE Mark

Bluetooth Profiles

BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping Supported

LE Dual Mode LE Link Laver

> LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 -Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

- 1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported.
- 2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of

transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

- 3. Check latest software/driver release for updates on supported security features.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Intel® 802.11a/b/g/n/ac Wireless LAN Standards (2x2) Wi-Fi® and Bluetooth® 5.0 Combo¹ Non-vPro

IEEE 802.11b IEEE 802.11q IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k

IEEE 802.11r IEEE 802.11v

IEEE 802.11a

Wi-Fi CERTIFIEDTM Interoperability

Technical Specifications

tions			
Frequency Band	• 802.11b/g/n 2.402 - 2.482 GHz		
Data Rates	 802.11a/n/ac 4.9 - 4.95 GHz (Japan) 5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz & 160MHz) 		
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM		
Security ³	 IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i WAPI 		
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)		
Roaming	IEEE 802.11 compliant roaming between access points		
Output Power ²	 802.11b: +18.5dBm minimum 802.11g: +17.5dBm minimum 802.11a: +18.5dBm minimum 802.11n HT20(2.4GHz): +15.5dBm minimum 802.11n HT40(2.4GHz): +14.5dBm minimum 802.11n HT20(5GHz): +15.5dBm minimum 802.11n HT40(5GHz): +14.5dBm minimum 802.11ac VHT80(5GHz): +11.5dBm minimum 802.11ac VHT160(5GHz): +11.5dBm minimum 		
Power Consumption	 Transmit mode 2.0 W Receive mode 1.6 W Idle mode (PSP) 180 mW (WLAN Associated) Idle mode 50 mW (WLAN unassociated) Connected Standby/Modern Standby: 10mW Radio disabled 8 mW 		
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode		
Receiver Sensitivity ⁴	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum		

802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum

Technical Specifications

Antenna type High efficiency antenna.

One embedded dual band 2.4/5 GHz antenna is provided to the card to support

WLAN communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard

Dimensions Type 2230: 2.3 x 22.0 x 30.0 mm

Type 1216: 1.67 x 12.0 x 16.0 mm

Weight Type 2230: 2.8 g

Type 126: 1.3 g

Operating Voltage 3.3v +/- 9%

Temperature Operating: 14° to 158° F (-10° to 70° C)

Non-operating: -40° to 176° F (-40° to 80° C)

Humidity Operating: 10% to 90% (non-condensing)

Non-operating: 5% to 95% (non-condensing)

Altitude Operating: 0 to 10,000 ft (3,048 m)

Non-operating: 0 to 50,000 ft (15,240 m)

LED Activity LED Amber - Radio OFF

LED OFF - Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2/5.0 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available Legacy: 0~79 (1 MHz/CH)

Channels BLE: 0~39 (2 MHz/CH)

Signaling Data Rate Legacy: 3 Mbps Signaling Data Rate 2.17 Mbps

BLE: 1 Mbps Signaling Data Rate 0.2 Mbps

1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with a

maximum transmit power of + 4 dBm for BR and EDR.

Power Consumption Peak (Tx) 330 mW

Peak (Rx) 230 mW

Selective Suspend 17 mW

Electrical Interface USB 2.0 compliant

Bluetooth Software

OSS 210 compliant

Supported

Microsoft Windows Bluetooth Software

Link Topology

Power Management Microsoft Windows ACPI, and USB Bus Support **Certifications** FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management Certifications ETS 300 328, ETS 300 826

Low Voltage Directive IEC950 UL, CSA, and CE Mark

Bluetooth Profiles

BT4.1-ESR 5/6/7 Compliance

Supported

LE Link Layer Ping LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising
LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

Technical Specifications

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 -Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

- 1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited.
- 2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
- 3. Check latest software/driver release for updates on supported security features.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

802.11 a/b/g/n/ac (2x2) Wi-Fi® and Bluetooth®	١
5.0	

Wireless LAN Standards IEE

IEEE 802.11a IEEE 802.11b

IEEE 802.11g IEEE 802.11n

IEEE 802.11ac

IEEE 802.11e IEEE 802.11h

IEEE 802.11i

IEEE 802.11k IEEE 802.11r

IEEE 802.11v

Interoperability Frequency Band Wi-Fi CERTIFIED™

• 802.11b/g/n 2.402 - 2.482 GHz

• 802.11a/n/ac

4.9 - 4.95 GHz (Japan)

5.15 - 5.25 GHz

5.25 - 5.35 GHz

5.47 - 5.725 GHz

5.825 - 5.850 GHz

Data Rates

• 802.11b: 1, 2, 5.5, 11 Mbps

• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz & 80MHz)

Modulation

Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security³

 IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only

• AES-CCMP: 128 bit in hardware

802.1x authentication

Technical Specifications

 WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certification

IEEE 802.11i

WAPI

Network Architecture

Models

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

Roaming IEEE 802.11 compliant roaming between access points

Output Power² ■ 802.11b: +18.5dBm minimum ■ 802.11g: +17.5dBm minimum

• 802.11a: +18.5dBm minimum

802.11n HT20(2.4GHz): +15.5dBm minimum
802.11n HT40(2.4GHz): +14.5dBm minimum
802.11n HT20(5GHz): +15.5dBm minimum
802.11n HT40(5GHz): +14.5dBm minimum
802.11ac VHT80(5GHz): +11.5dBm minimum

• 802.11ac VHT160(5GHz): +11.5dBm minimum

Power Consumption • Transmit mode: 2.0 W

• Receive mode: 1.6 W

Idle mode (PSP) 180 mW (WLAN Associated)
Idle mode: 50 mW (WLAN unassociated)
Connected Standby/Modern Standby: 10mW

Radio disabled: 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity⁴ 802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard with CNVi Interface

Dimensions Type 2230: 2.3 x 22.0 x 30.0 mm

Type 1216: 1.67 x 12.0 x 16.0 mm

Weight Type 2230: 2.8 g

Type 126: 1.3 g

Operating Voltage 3.3v +/- 9%

Temperature Operating: 14° to 158° F (-10° to 70° C)

Non-operating: -40° to 176° F (-40° to 80° C)

Humidity Operating: 10% to 90% (non-condensing)

Non-operating: 5% to 95% (non-condensing)

Altitude Operating: 0 to 10,000 ft (3,048 m)

Non-operating: 0 to 50,000 ft (15,240 m)

LED Activity LED Amber - Radio OFF

LED OFF - Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

Technical Specifications

Bluetooth Specification 4.0/4.1/4.2/5.0 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available

Channels

Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)

Signaling Data Rate Legacy: 3 Mbps Signaling Data Rate 2.17 Mbps

BLE: 1 Mbps Signaling Data Rate 0.2 Mbps

1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with a

maximum transmit power of + 4 dBm for BR and EDR.

Power Consumption Peak (Tx) 330 mW

Peak (Rx) 230 mW

Selective Suspend 17 mW

Bluetooth Software

Supported Link Topology Microsoft Windows Bluetooth Software

Power Management Microsoft Windows ACPI, and USB Bus Support **Certifications** FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management

Certifications

ETS 300 328, ETS 300 826 Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles

Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping LE Dual Mode

LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 -Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

- 1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited.
- 2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
- 3. Check latest software/driver release for updates on supported security features.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Technical Specifications

Realtek RTK8111HSH 10/100/1000 Integrated NIC

Connector RJ-45
System Interface PCIe + SMBus

Ethernet Features 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)

100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)

Auto-Negotiation (Automatic Speed Selection)

Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100

Mbit/s

IEEE 802.1p QoS (Quality of Service) Support

IEEE 802.1q VLAN support

IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)

IEEE 802.3az EEE (Energy Efficient Ethernet)

Power Management ACPI compliant - multiple power modes

Situation-sensitive features reduce power consumption

Advanced link down power saving for reducing link down power consumption

Performance Features TCP/IP/UDP Checksum Offload (configurable)

Protocol Offload (ARP & NS)

Large send offload and Giant send offload

Receiving Side Scaling Jumbo Frame 9K

Manageability Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft

Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)

PXE 2.1 Remote Boot

Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x,

clause 30)

Comprehensive diagnostic and configuration software suite

Virtual Cable Doctor for Ethernet cable status

Management Interface Auto MDI/MDIX Crossover cable detection

POWER

HP 45 W Smart AC Adapter **Dimensions (H x W x D)** 3.74 x 1.57 x 1.04 in (9.5 x 4 x 2.65 cm)

Weight 0.386 lb (175 g) max

Not including power cord. Power cord varies by country

Input 90 to 265 VAC

Input Efficiency 87.74% at 115VAC and 88.4% at 230VAC

Input frequency range 47 to 63 Hz
Input AC current 1.4 A at 90 VAC

Output Output power 45 W

DC output 19.5 V

Hold-up time 5 msec at 115 VAC input

Output current limit <8.0 A

Connector 4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cords

Environmental Design Operating temperature 32° to 95° F (0° to 35° C)

Non-operating (storage) -4° to 185° F (-20° to 85° C)

temperature

Altitude 0 to 16,400 ft (0 to 5,000 m)

Humidity 20% to 95% Storage Humidity 10% to 95%

Technical Specifications

EMI and Safety Certifications

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC

Class B. CISPR22 Class B. CCC. NOM-1 NYCE.

* MTBF - over 200.000 hours at 25°C ambient condition.

HP 65 W Smart AC adapter

Dimensions 90 x 51 x 28.5 mm Weight 220 a +/- 10 a

Not including power cord. Power cord varies by country

Input **Input Efficiency** 88.0 % at 115 VAC and 89.0 % at 230VAC

> Input frequency range 47 ~ 63 Hz 1.7 A at 90 VAC **Input AC current**

Output **Output power** 65 W

> DC output 19.5 V

Hold-up time 5 msec at 115 VAC input

Output current limit <11.0 A

Connector 4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cords

Environmental Design Operating temperature 32°F to 95°F (0° to 35°C)

Non-operating (storage) -4°F to 185°F (-20° to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

EMI and Safety

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, Certifications

SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC

Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 200.000 hours at 25°C ambient condition.

HP 65W EM Smart AC adapter

Dimensions 102 x 55 x 30 mm Weight 270 q +/- 10 q

Not including power cord. Power cord varies by country

Input **Input Efficiency** 87% min at 115V/230V

> Input frequency range 47 to 63 Hz

Input AC current 1.7 A at 90 VAC and maximum load

Output DC output 65 W (19.5V/3.33A)

> Hold-up time 5 msec at 115 V input

Output current limit <11A, Over voltage protection- 29V max

automatic shutdown

Connector 4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cords

32°F to 95°F (0° to 35°C) **Environmental Design** Operating temperature

Non-operating (storage) -4°F to 185°F (-20° to 85°C)

temperature

Altitude 0 to 5,000 m Humidity 0% to 95%

Technical Specifications

Storage Humidity 0% to 95%

EMI and Safety Certifications

*CE Mark - EMC directives

*Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE; Reliability - failure rate of less than

0.1% annually within the first three years of operation. *MTBF - over 200.000 hours at 25°C ambient condition.

AC Adapter 65 Watt nPFC Dimensions **USB Type-C®**

74 x 74 x 28.5 mm Weight 245 a +/- 10 a

Not including power cord. Power cord varies by country

Input **Input Efficiency** 81.5% min at 115 Vac/ 230Vac @ 5V/3A

> 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 10V/5A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A

Input frequency range 47 ~ 63 Hz

Input AC current 1.7 A at 90 VAC and maximum load

Output **Output power** 65 W

> DC output 5V/9V/10V/12V/15V/20V Hold-up time 5ms at 115 VAC input

Output current limit <8.0 A

USB Type-C® Connector

32° F to 95° F (0° to 35° C) **Environmental Design** Operating temperature

> Non-operating (storage) -4° F to 185° F (-20° to 85° C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 5% to 95% 5% to 95% **Storage Humidity**

EMI and Safety Certifications

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1,

SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC

Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 100,000 hours at 25°C ambient condition.

Technical Specifications

AC Adapter 45 Watt nPFC USB type C®

Dimensions 94.0 mm x 40.0 mm x 26.5 mm

Weight 192.5 g +/-10 g

Not including power cord. Power cord varies by country

Input Input Efficiency Average Efficiency of 25%, 50%, 75%, 100%

load condition with 115Vac/230Vac Spec:

5V: 81.5% 9V: 86.7% 12V: 87.41% 15V: 87.8%

Input frequency range 47 ~ 63 Hz

Input AC current Max. 1.4 A at 90 VAC

Output power 5V/15W

9V/27W 12V/36W 15V/45W

DC output 5V/9V/12V/15V **Hold-up time** 5ms at 115 VAC input

Output current limit <5.0 A

Connector USB Type-C®

Environmental Design Operating temperature 32°F to 95°F (0° to 35°C)

Non-operating (storage) -4°F to 185°F (-20° to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

EMI and Safety Certifications

Output

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B. CISPR22 Class B. CCC. NOM-1 NYCE* MTBF - over 200.000 hours at

25°C ambient condition.

3 Cell WHr 45 Long Life -Polymer HP Fast Charge Technology¹ **Dimensions (H x W x L)** 6.0 x 184.7 x 88.9 mm

Weight 0.22 kg (0.48lb)

Cells/Type 3cell Lithium-Ion

Energy Voltage 11.55 V

Amp-hour capacity 3.900 Ah
Watt-hour capacity 45 Wh

Temperature Operating (Charging) 32° to 113° F (0° to 45° C)

Operating (Discharging) 14° to 122° F (-10° to 60° C)

Optional Travel Battery

Available

No

^{1.} Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode when used with the power adapter provided with the notebook. After charging has reached 50% capacity, charging speed will return to normal. Charging time may vary +/-10% due to System tolerance.

Technical Specifications

Country of Origin

China

Options and Accessories (sold separately and availability may vary by country)

Туре	Description	Part Number
Cases	HP Essential Top Load Case	H2W17AA
	HP Essential Backpack (up to 15.6")	H1D24AA
	HP 17.3 Business Backpack	2SC67AA
Docking	HP USB-C Mini Dock	1PM64AA
Docking	HP Thunderbolt Dock 120W G2	2UK37AA
	HP TB Dock G2 w/ Combo Cable	3TR87AA
	HP TB Dock 120W G2 w/Audio	3YE87AA
	·	
	HP TB Dock C3 Combo Cable	3XB94AA
	HP TB Dock G2 Combo Cable	3XB96AA
	HP TB Dock G2 Audio Module	3AQ21AA 5TW13AA
	HP USB-C/A Universal Dock G2	
	HP USB-C Dock G5	5TW10AA
Input / Output	HP USB Essential Keyboard and Mouse	H6L29AA
	HP Bluetooth Travel Mouse	6SP30AA
	HP Ultra Mobile Wireless Mouse	H6F25AA
	HP Comfort Grip Wireless Mouse	H2L63AA
	HP 3-Button USB Laser Mouse	H4B81AA
	HP USB Travel Mouse	G1K28AA
	HP HDMI to DVI Adapter	F5A28AA
	HP Elite USB-C Hub	4WX89AA
	HP USB-C Travel Hub G2	7PJ38AA
Power	HP 45W Smart AC Adapter 4.5mm	H6Y88AA
	65W Smart Power Adapter (w/ 4.5mm to 7.5mm DC dongle)	Н6Ү89АА
	HP 65W Slim AC Adapter	H6Y82AA
	HP 65W USB-C Slim Power Adapter	3PN48AA
	HP 65W USB-C Power Adapter	1HE08AA
	HP 45W USB-C Power Adapter	1HE07AA
	HP USB-C Power Bank	2NA10AA
Storage	HP External USB Optical Drive	F2B56AA
Security	HP Keyed Cable Lock 10mm	T1A62AA
,	HP Sure Key Cable Lock	6UW42AA
Displays	HP E223d Docking Monitor	5VT82A8/5VT82AA
Displays	HP E243d Docking Monitor	1TJ76AA
	HP E273d Docking Monitor	5WN63A8/5WN63AA
	HP EliteDisplay E244d Monitor	6PA50A8/6PA50AA
	HP EliteDisplay E274d Monitor	6PA56A8/6PA56AA
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Summary of Changes

Date of change:	Version History:		Description of change:
April 29, 2020	From V1 to V2	Updated	MIL-STD 810G to MIL-STD 810H
May 7, 2020	From V2 to V3	Updated	Ethernet Section
May 28, 2020	From V3 to V4	Updated	Ports and Memory Section
August 31, 2020	From v4 to V5	Updated	Processors Section
September 22, 2020	V5 to V6	Updated	Display Section

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